



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20130521000
TL4242-Q1 storage temperature - CMS C1305067
Information Only**

Date: 5/23/2013
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a specification for a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only. Please see the attachment details for the planned implementation date.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130521000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TL4242QKTTRQ1	null
TL4242TDRJRQ1	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130521000	PCN Date:	05/23/2013
Title:	TL4242-Q1 storage temperature - CMS C1305067		
Customer Contact:	PCN Manager	Phone:	+1(214) 480-6037
Dept:	Quality Services		
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input checked="" type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

PCN Details	
Description of Change:	
Texas Instruments publication SLVS732 has changed as described below: Page 3, Absolute Maximum Ratings table, T _{STG} =Storage Temperature minimum has changed from -50C to -55C.	
Reason for Change:	
Make typographical correction.	
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):	
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.	
Changes to product identification resulting from this PCN:	
None	
Product Affected:	
TL4242QKTTRQ1 TL4242TDRJRQ1 TL4242QDRJRVO	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com